

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2003-261688

(43)Date of publication of application : 19.09.2003

(51)Int.Cl. C08J 5/04
C08K 7/06
C08L101/00
H01B 1/24

(21)Application number : 2002-060632

(71)Applicant : YUKA DENSHI CO LTD

(22)Date of filing : 06.03.2002

(72)Inventor : SAGISAKA KOICHI

(54) SEMI-CONDUCTIVE RESIN MOLDED ARTICLE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semi-conductive resin molded article having a uniform resistance value in the semi-conductive region.

SOLUTION: The semi-conductive molded article is comprised by molding a conductive thermal plastic resin composition composed by mixing (C) the thermal plastic resin and/or a thermal plastic elastomer of 0.1-80 pts.wt. except the component (C) to a conductive resin component comprising (A) a matrix thermal plastic resin and (B) a fine carbon fiber having an average fiber diameter of 200 nm or less of 0.1-20 wt.%. The component 3 (C) is not completely dissolved with the component 1 (A) and is dispersed in a sea-island form, the component 3 (C) forms a dispersion phase in an island form and an average value of the short diameter R_{min} of the dispersion phase of the component 3 (C) is 10 μm or less.

